

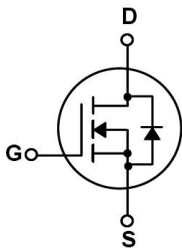
/ Descriptions

/ Features

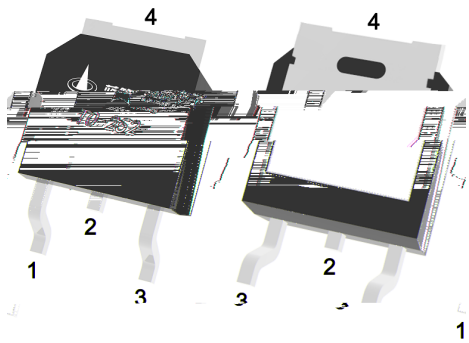
$\leq$	Ω	Ω
$\leq$	Ω	Ω

/ Applications

/ Equivalent Circuit



/ Pinning



/ Marking

/ Absolute Maximum Ratings(Tc=25)

/ Electrical Characteristics(Tc=25)

		μ				
						μ
						Ω
						μ

/ Electrical Characteristics(Tc=25)

		Ω μ				
-						μ
-						
						Ω

/ Electrical Characteristic Curve

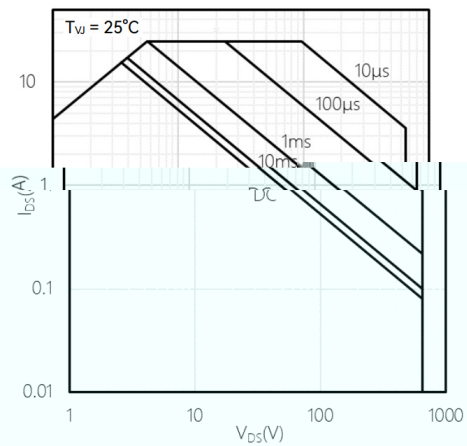


Fig1. Safe operating area (SOA)

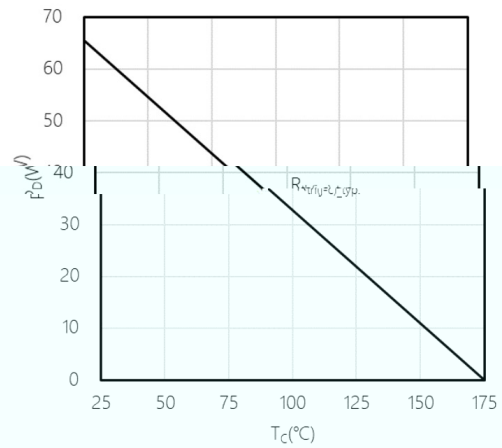
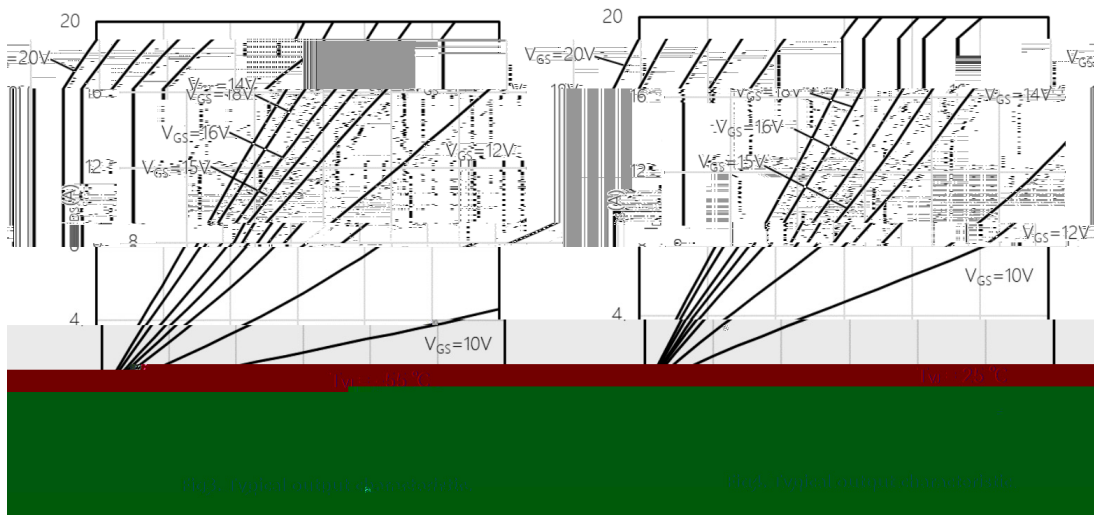
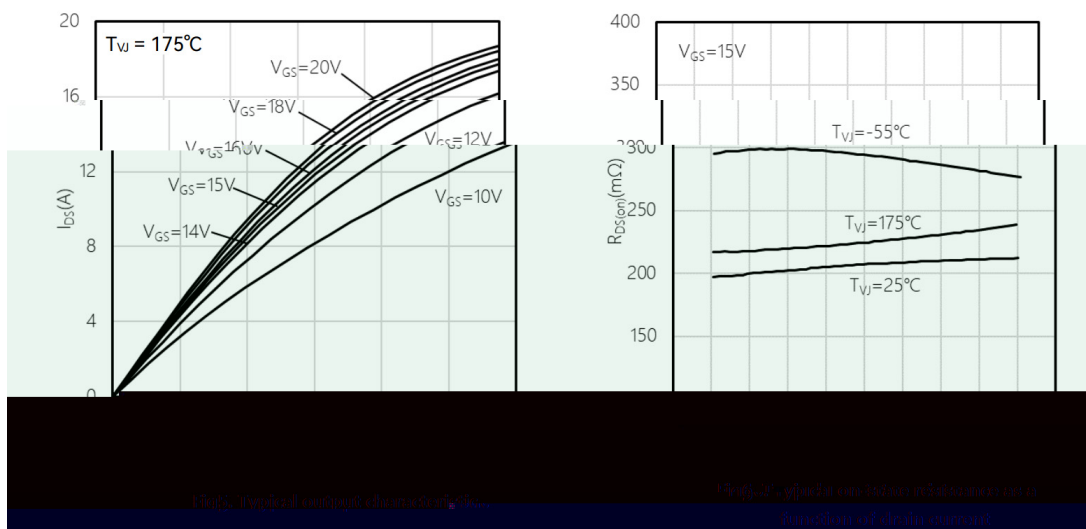


Fig2. Power dissipation



Note: Vds is not to exceed Vdsmax

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/ Electrical Characteristic Curve

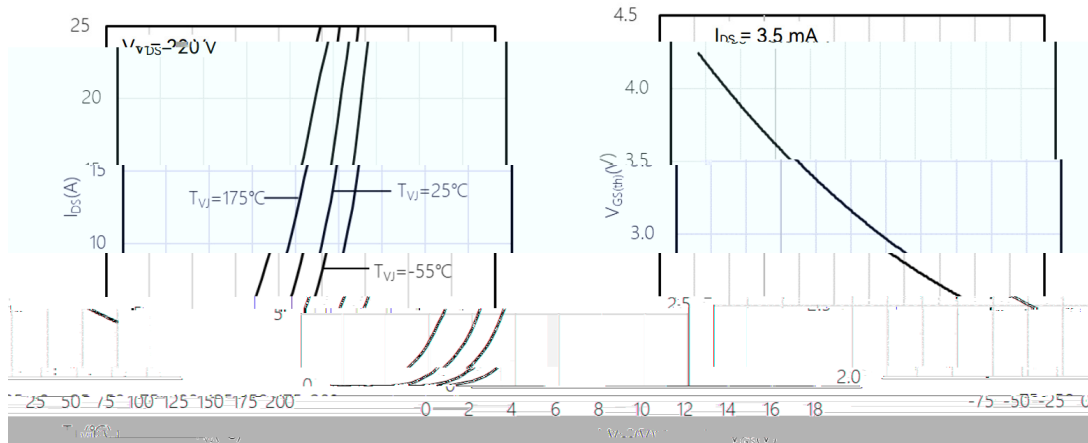
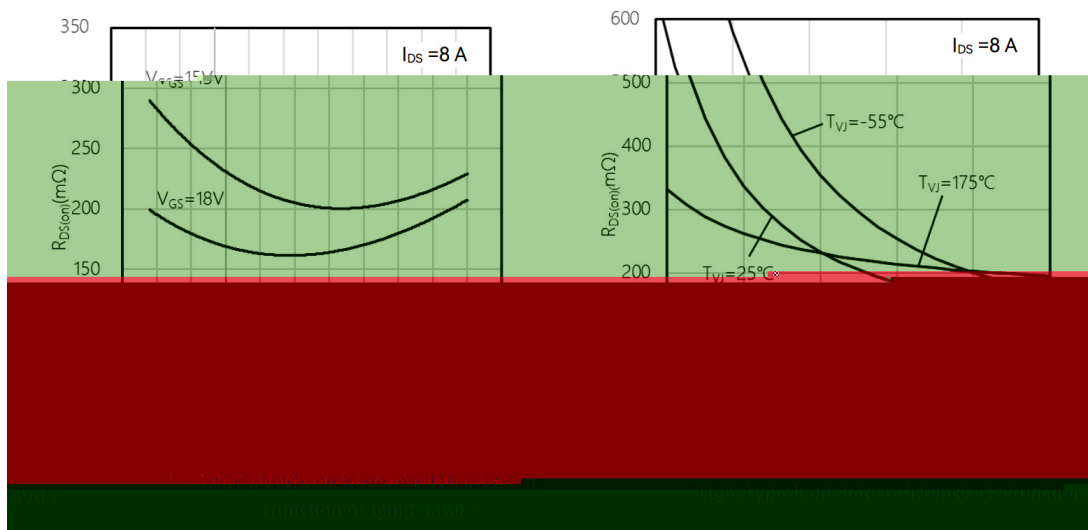


Fig10. Typical gate-source threshold voltage as a function of junction temperature

Fig9. Typical transfer characteristic

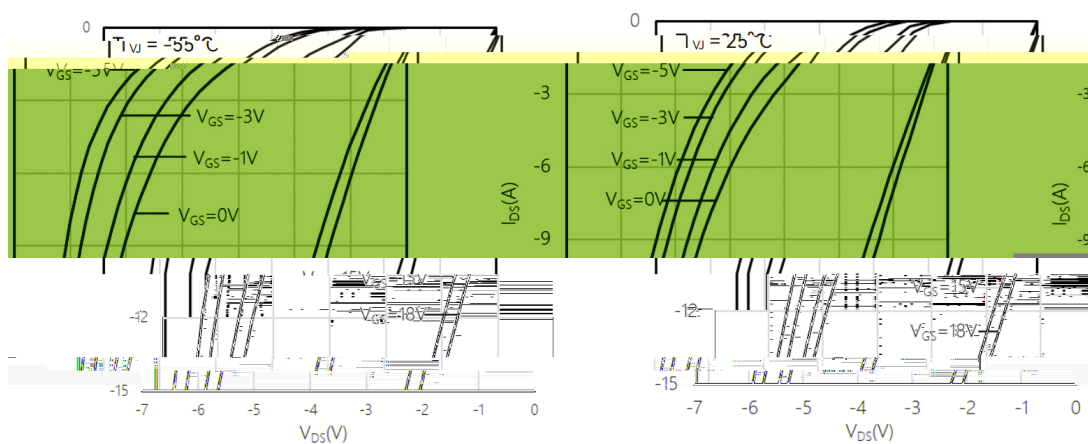
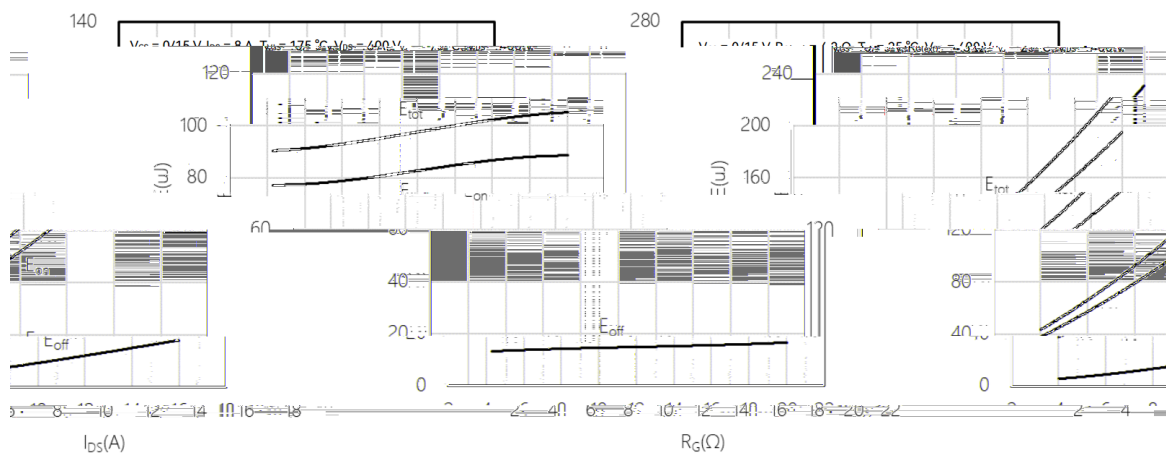
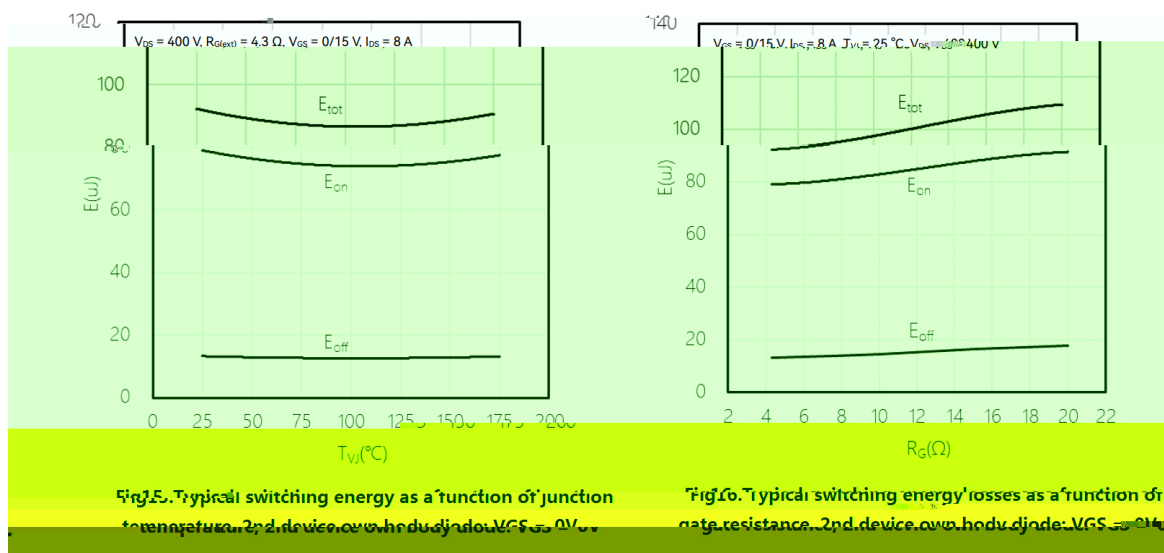
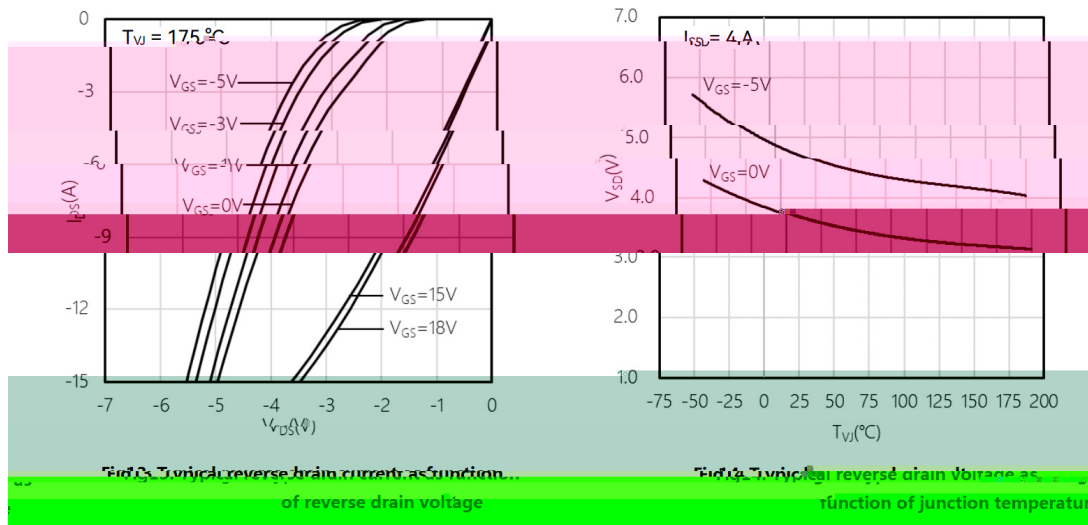


Fig11. Typical reverse drain current as function of reverse drain voltage

Fig12. Typical reverse drain current as function of reverse drain voltage

/ Electrical Characteristic Curve

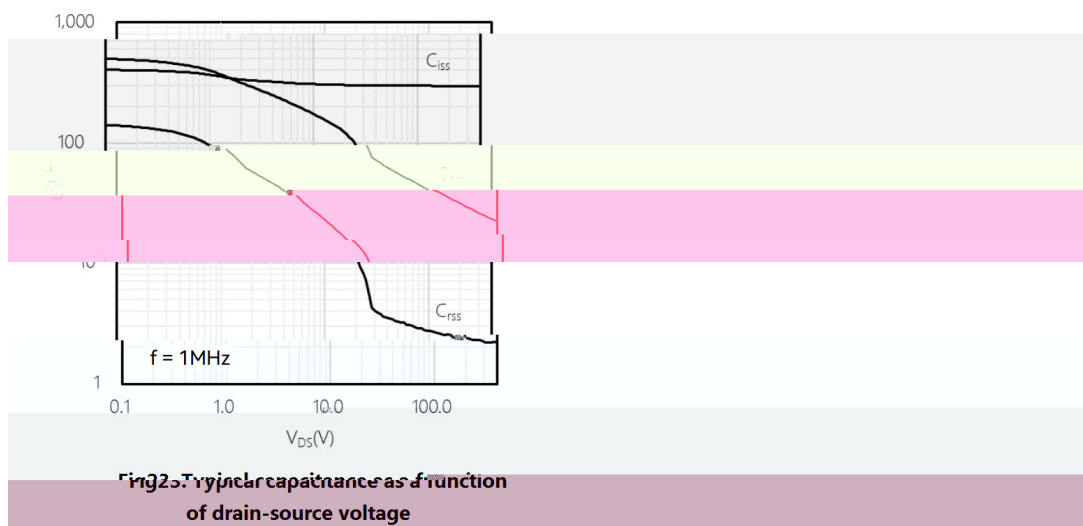
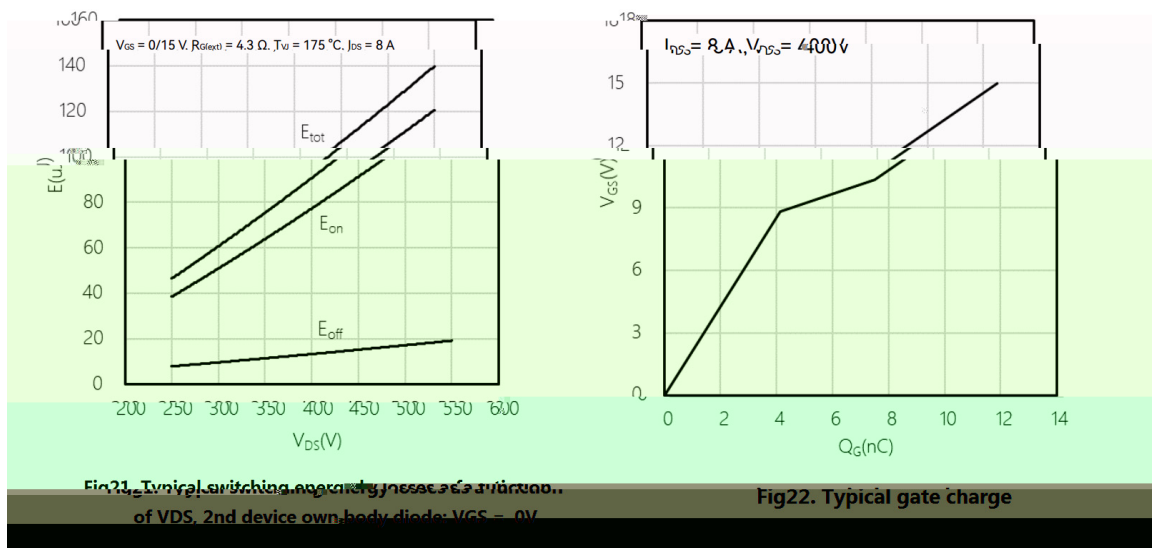
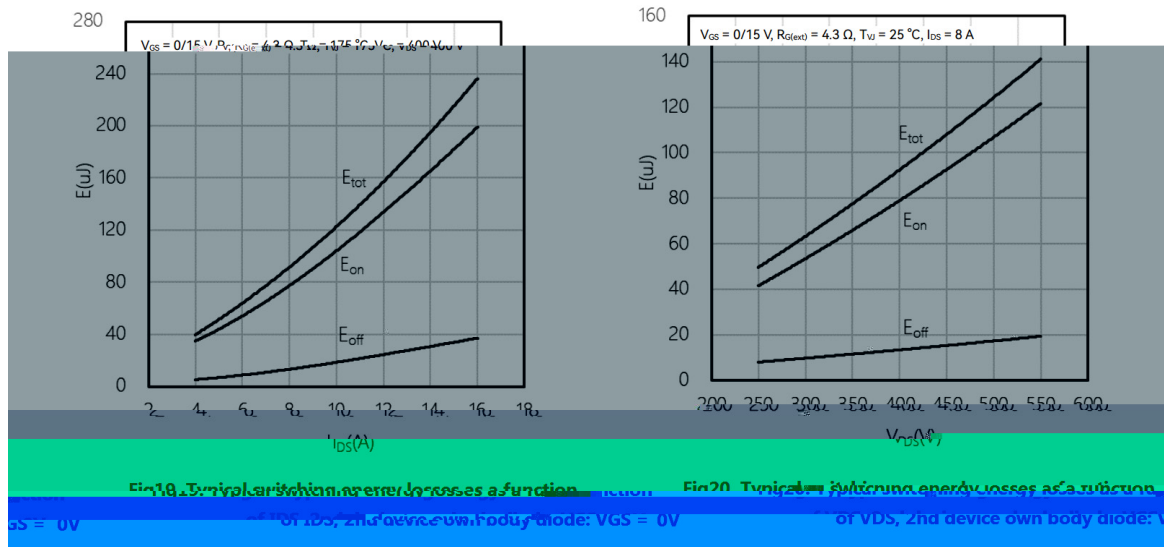


switching energy losses as a function of drain current, 2nd device own body diode: $V_{GS} = 0\text{V}$

Fig17. Typical switching energy losses as a function of gate resistance, 2nd device own body diode: $V_{GS} = 0\text{V}$

Fig18. Typical switching energy losses as a function of I_{DS} , 2nd device own body diode: $V_{GS} = 0\text{V}$

/ Electrical Characteristic Curve



/ Electrical Characteristic Curve

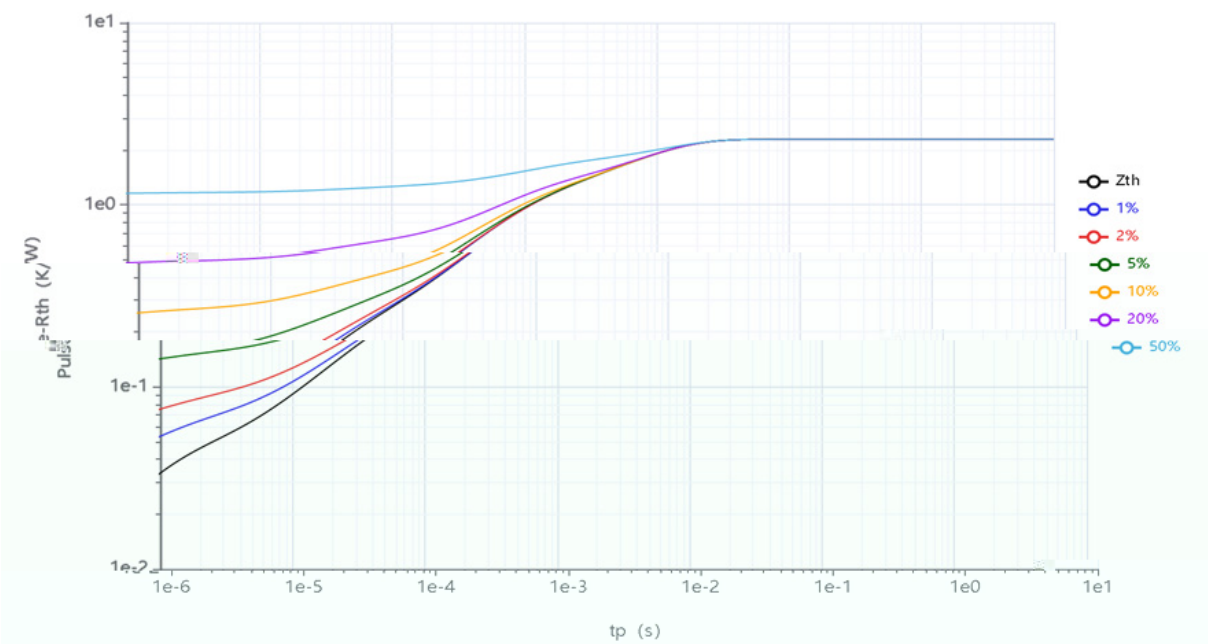
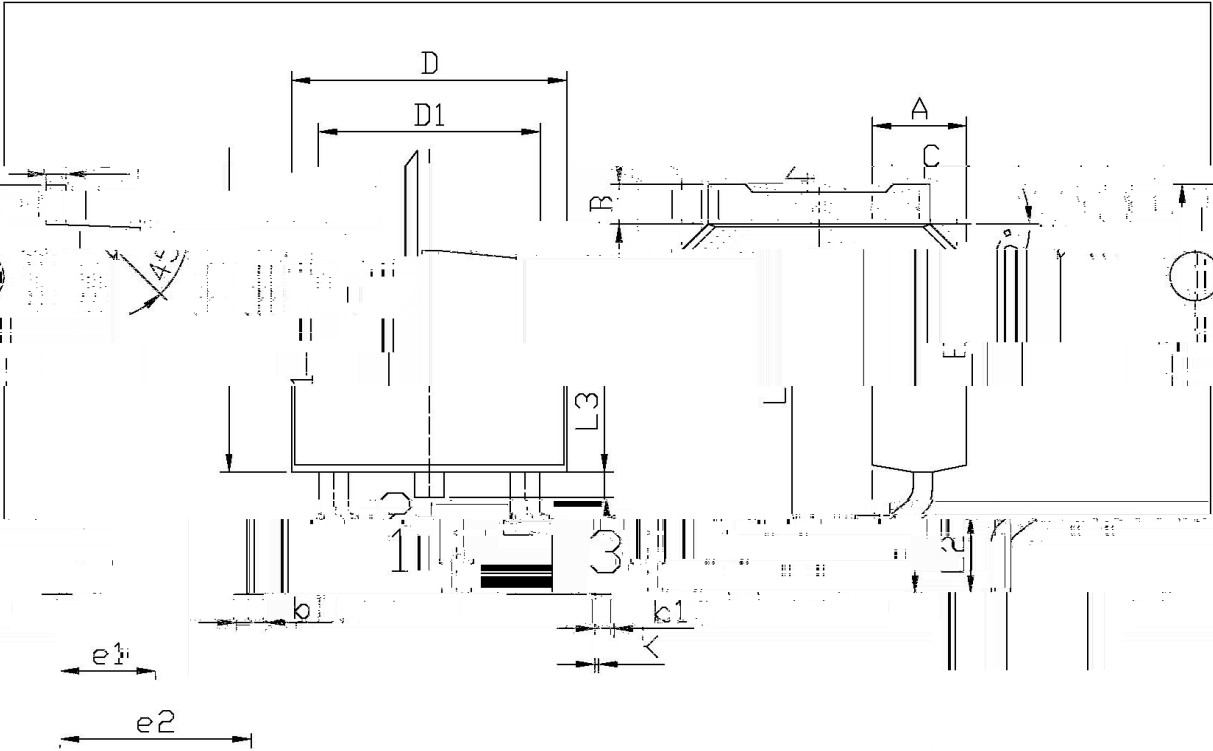


Fig24. Transient thermal resistance (MOSFET)

/ Package Dimensions



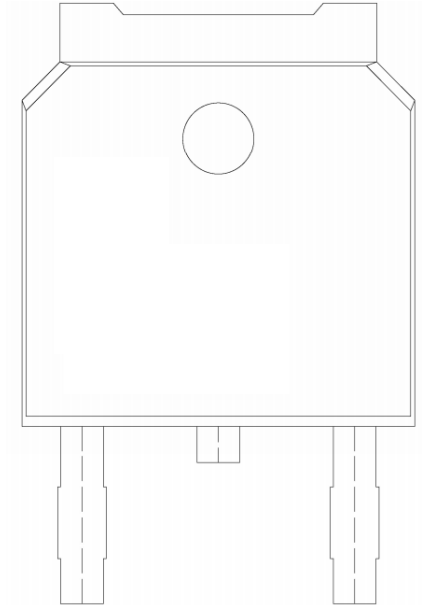
单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	5.95	6.25	A	2.20	2.40
e1	2.24	2.34	B	0.95	1.25
e2	4.40	4.73	C	0.70	0.90
D	9.85	10.35	E	0.51	0.45
L3	0.45	0.55	D1	1.70	2.00
K	0.00	0.10	D1	6.45	6.75
			D1	5.10	5.50

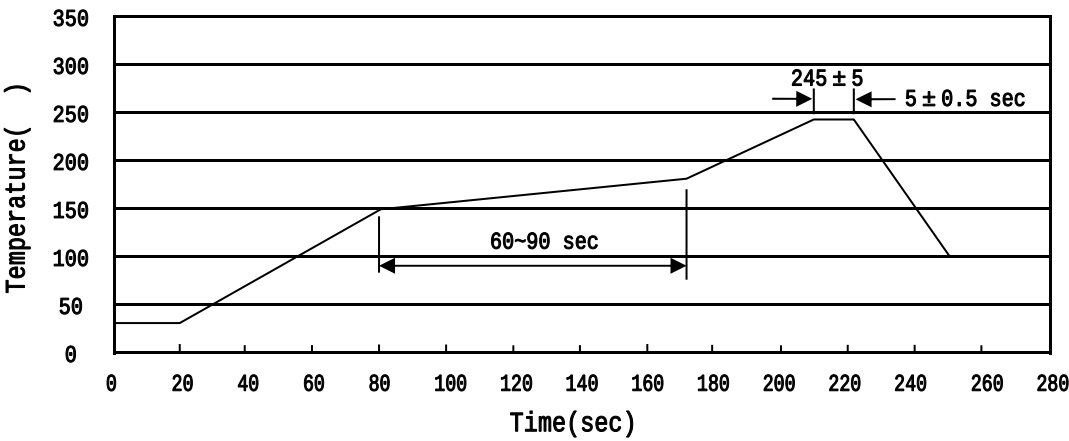
-252

T0

/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

/ Notices